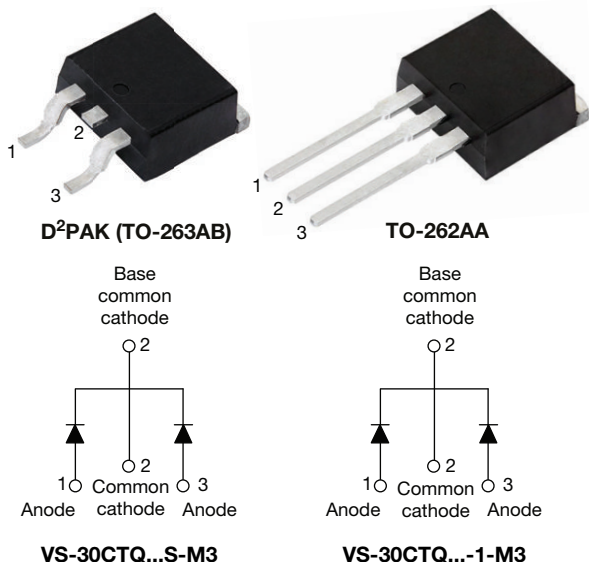


High Performance Schottky Rectifier, 2 x 15 A



RoHS
COMPLIANT
HALOGEN
FREE



FEATURES

- 150 °C T_J operation
- Center tap configuration
- Very low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

PRIMARY CHARACTERISTICS

I _{F(AV)}	2 x 15 A
V _R	50 V, 60 V
V _F at I _F	0.56 V
I _{RM} typ.	45 mA at 125 °C
T _J max.	150 °C
E _{AS}	13 mJ
Package	D ² PAK (TO-263AB), TO-262AA
Circuit configuration	Common cathode

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
I _{F(AV)}	Rectangular waveform	30	A
V _{RRM}		50/60	V
I _{FSM}	t _p = 5 μs sine	1000	A
V _F	15 A _{pk} , T _J = 125 °C (per leg)	0.56	V
T _J	Range	-55 to +150	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-30CTQ050S-M3 VS-30CTQ050-1-M3	VS-30CTQ060S-M3 VS-30CTQ060-1-M3	UNITS
Maximum DC reverse voltage	V _R	50	60	V
Maximum working peak reverse voltage	V _{RWM}			

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 105\text{ }^{\circ}\text{C}$, rectangular waveform	30	A
per device			15	
per leg	I_{FSM}	5 μs sine or 3 μs rect. pulse	1000	
Maximum peak one cycle non-repetitive surge current per leg See fig. 7		10 ms sine or 6 ms rect. pulse	260	
Non-repetitive avalanche energy per leg	E_{AS}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_{AS} = 1.50\text{ A}$, $L = 11.5\text{ mH}$	13	mJ
Repetitive avalanche current per leg	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical	1.50	A

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop per leg See fig. 1	$V_{FM}^{(1)}$	15 A	0.62	V
		30 A	0.82	
		15 A	0.56	
		30 A	0.71	
Maximum reverse leakage current per leg	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	0.80	mA
		$T_J = 125\text{ }^{\circ}\text{C}$	160	
Typical reverse leakage current	$I_{RM}^{(1)}$	$T_J = 125\text{ }^{\circ}\text{C}$	45	mA
Threshold voltage	$V_{F(TO)}$	$T_J = T_J$ maximum	0.39	V
Forward slope resistance	r_t		8.47	m Ω
Maximum junction capacitance per leg	C_T	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^{\circ}\text{C}$	720	pF
Typical series inductance per leg	L_S	Measured lead to lead 5 mm from package body	8.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R	10 000	V/ μs

Note(1) Pulse width < 300 μs , duty cycle < 2 %**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-55 to 150	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case per leg	R_{thJC}	DC operation	3.25	$^{\circ}\text{C/W}$
Maximum thermal resistance, junction to case per package			1.63	
Typical thermal resistance, case to heatsink	R_{thCS}	Mounting surface, smooth and greased	0.50	
Approximate weight			2	g
			0.07	oz.
Mounting torque	minimum		6 (5)	kgf · cm (lbf · in)
	maximum		12 (10)	
Marking device		Case style D ² PAK (TO-263AB)	30CTQ050S 30CTQ060S	
		Case style TO-262AA	30CTQ050-1 30CTQ060-1	

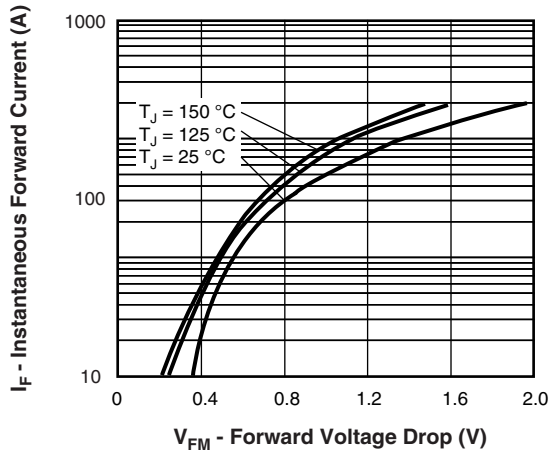


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

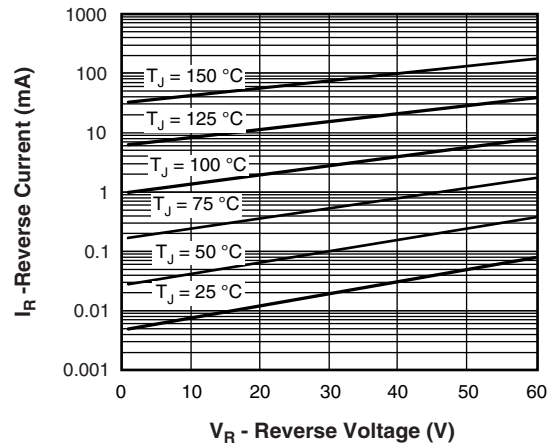


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

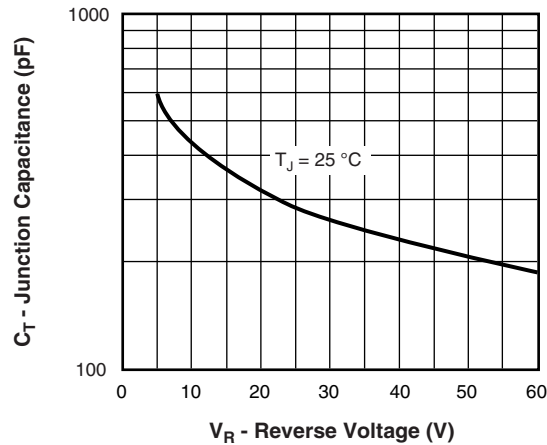


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

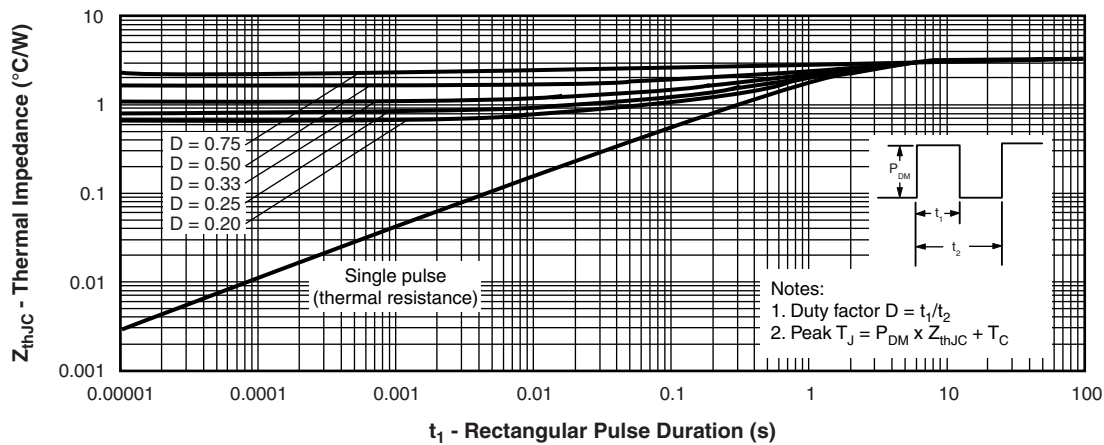


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

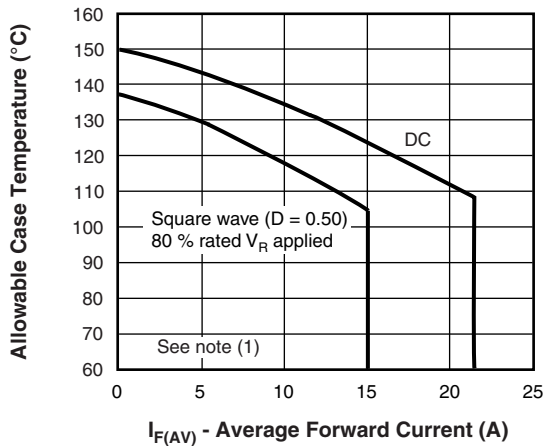


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

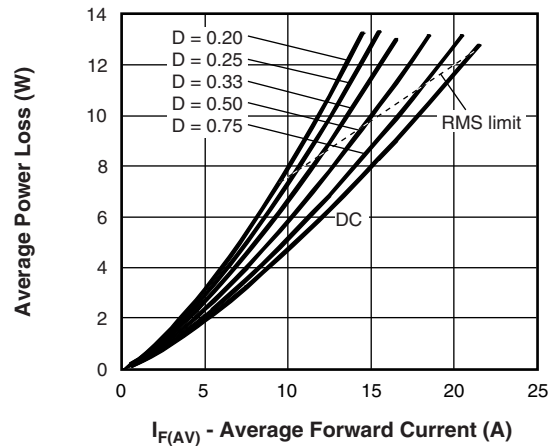


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

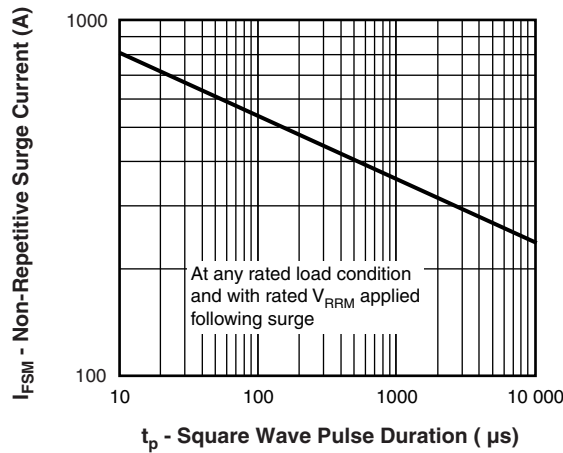


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

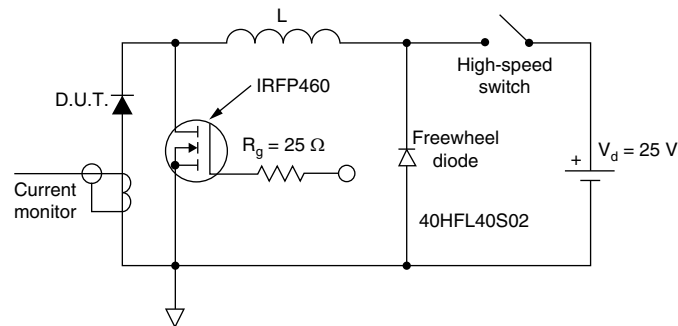


Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 10 V$



ORDERING INFORMATION TABLE

Device code	VS-	30	C	T	Q	060	S	TRL	-M3
	1	2	3	4	5	6	7	8	9

- | | | |
|----------|---|--|
| 1 | - | Vishay Semiconductors product |
| 2 | - | Current rating (30 A) |
| 3 | - | Circuit configuration: C = common cathode |
| 4 | - | T = TO-220 |
| 5 | - | Schottky "Q" series |
| 6 | - | Voltage ratings |
| 7 | - | • S = D ² PAK (TO-263AB)
• -1 = TO-262AA |
| 8 | - | • None = tube
• TRL = tape and reel (left oriented - for D ² PAK (TO-263AB) only)
• TRR = tape and reel (right oriented - for D ² PAK (TO-263AB) only) |
| 9 | - | -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free |
- 050 = 50 V

060 = 60 V

ORDERING INFORMATION

PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-30CTQ050S-M3	50	Antistatic plastic tubes
VS-30CTQ050STRR-M3	800	13" diameter plastic tape and reel
VS-30CTQ050STRL-M3	800	13" diameter plastic tape and reel
VS-30CTQ050-1-M3	50	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS

Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164
	TO-262AA	www.vishay.com/doc?96165
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444
	TO-262AA	www.vishay.com/doc?95443
Packaging information		www.vishay.com/doc?96424



D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

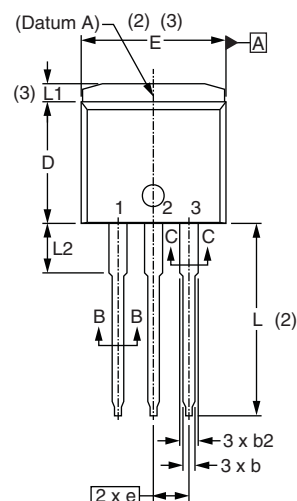
Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

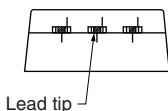
TO-262

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262

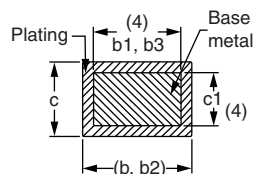
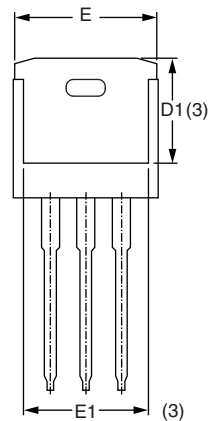
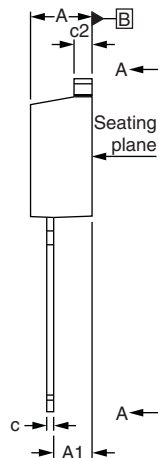


$\Phi 0.010 \text{ (M)} \text{ (B)}$



Lead assignments

- Diodes**
 1. - Anode (two die)/open (one die)
 2., 4. - Cathode
 3. - Anode



Section B - B and C - C
Scale: None

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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